

ATTORNEY DOCKET NO: 70234

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#4

Applicant : AZDASHT
Serial No :
Confirm. No. :
Filed :
For : METHOD AND DEVICE...
Art Unit :
Examiner :
Dated : July 17, 2001

Hon. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Attached please find Form PTO-1449 together with the references as stated in the specification.

- IBM Technical Disclosure Bulletin Vol. 34, No. 11, pp. 362-363 cited in the corresponding German application examination. This bulletin describes a manufacturing process for attaching circuit chips to flexible connection substrates.

- US 4,906,812 cited in the international search report with respect to claim 8 of the PCT application. The citation stated: document of particular relevance; the claimed invention cannot be considered to involve an innovative step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art.

- JP 60 162 574 A cited in the international search report with respect to claims 1-4, 6, 7 and 9-12 of the PCT application, the citation stated: document of particular relevance; the

claimed invention cannot be considered to involve an innovative step when the document is taken alone. And further cited in the international search report with respect to claims 5 and 8 of the PCT application, the further citation stated: document of particular relevance; the claimed invention cannot be considered to involve an innovative step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art. The only translation available at this time is the abstract.

- WO 97/12714 A cited in the international search report with respect to claims , 6 and 10 of the PCT application, the citation stated: document of particular relevance; the claimed invention cannot be considered to involve an innovative step when the document is taken alone. And further cited in the international search report with respect to claim 5 of the PCT application, the further citation stated: document of particular relevance; the claimed invention cannot be considered to involve an innovative step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art. The only translation available at this time is the abstract.

- JP 61 219 467 A cited in the international search report with respect to claims 1-4, 6 and 7 of the PCT application, the citation stated: document of particular relevance; the claimed invention cannot be considered to involve an innovative step when the document is taken alone. The only translation available at this time is the abstract.

- JP 07 142 854 A cited in the international search report with respect to claim 1 of the PCT application, the citation stated: document of particular relevance; the claimed invention cannot be considered to involve an innovative step when the document is taken alone. The only

translation available at this time is the abstract.

- DE 44 46 289 A1 cited in the corresponding German application examination. This patent describes a process for joining substrates together with a joining material, where the joining material is heated by an energy beam of such wavelength that the substrates appear transparent to the energy beam, which is absorbed by the joining material after it passes through the substrates. No translation is available at this time.

- DE 195 04 967 A1 cited in the corresponding German application examination. This patent describes a process for thermally bonding contact elements of a flexible film substrate to metallized contact areas of an electronic component by passing laser radiation through a carrier layer and onto a contact element which then absorbs the energy of the laser. No translation is available at this time.

- DE 195 20 336 A1 cited in the corresponding German application examination. This patent describes a method for soldering multi-pole electronic components to a circuit carrier using laser energy for soldering. No translation is available at this time.

- EP 0 387 066 A1 cited in the corresponding German application examination. This patent describes a method for adhesive bonding of circuits where an adhesive layer is cured by heating.

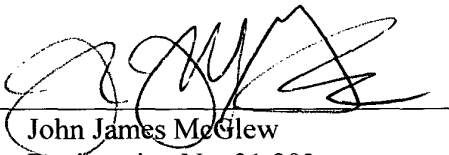
- EP 0 756 323 A2 (corresponding to US 5,717,477) cited in the corresponding German application examination. This patent describes a method of adhesive bonding electronic components to a substrate where contact bumps are used to make contact between the electronic component, and the substrate. No translation is available at this time.

- DE 197 49 909 A1 cited in the corresponding German application examination. This patent describes a method for making a plurality of connections between optical fiber ends using laser energy. No translation is available at this time.

- JP 05-259-220 A cited in the corresponding German application examination. This abstract describes a method for eliminating loss of laser energy and reducing joint defects with the use of an optical waveguide with a transparent member. The only translation available at this time is the abstract.

Favorable action on the merits of this application is respectfully requested.

Respectfully submitted
for Applicant,

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JJM:esd

Enclosed: PTO-1449 Form

DATED: July 17, 2001
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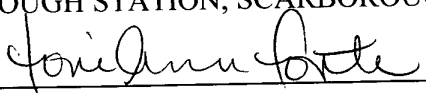
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